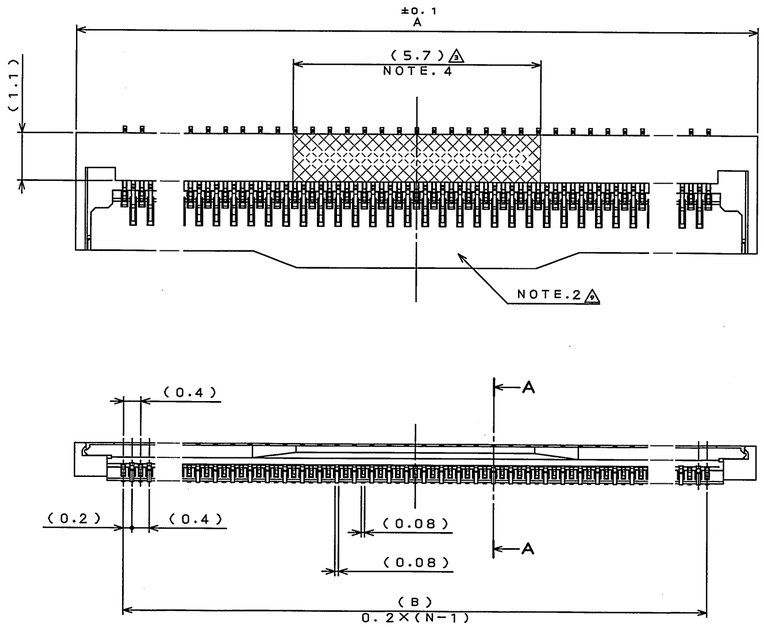
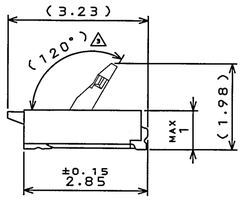
図面番号(DRAWING NO.) SJ108178

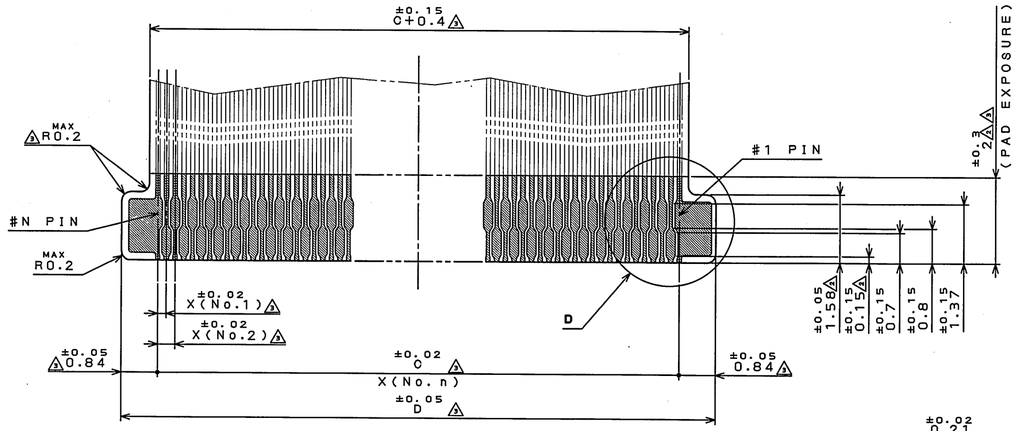
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
8	25.May.2010	069988	Added New Items		K.ASHIBU	T.NEMOTO	A.NATORI
9	9.Sep.2010	070484	Changed Marking Position Of Lot Number		K.ASHIBU	T.NEMOTO	A.NATORI
10	27.Oct.2010	070937	Changed Applicable F.P.C. Dimension(REF.)		K.ASHIBU	T.NEMOTO	a.natori



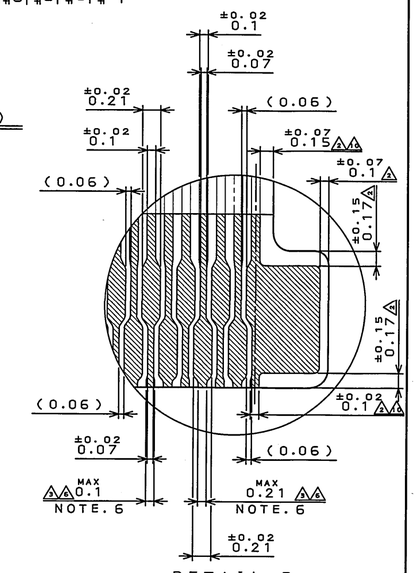
△ TABLE 3.DIMENSIONS

NO.	X
1	0.2
2	0.4
3	0.6
.	.
.	.
n	0.2×(n-1)

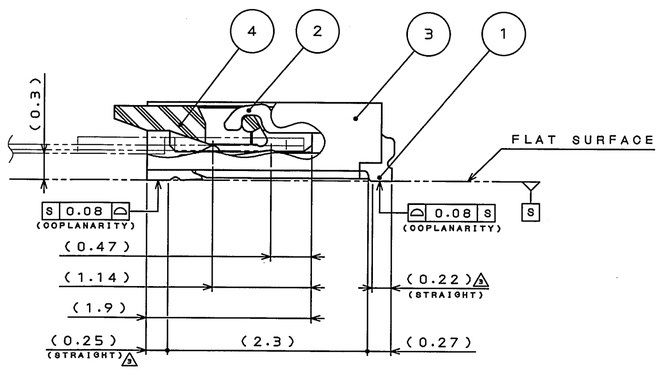




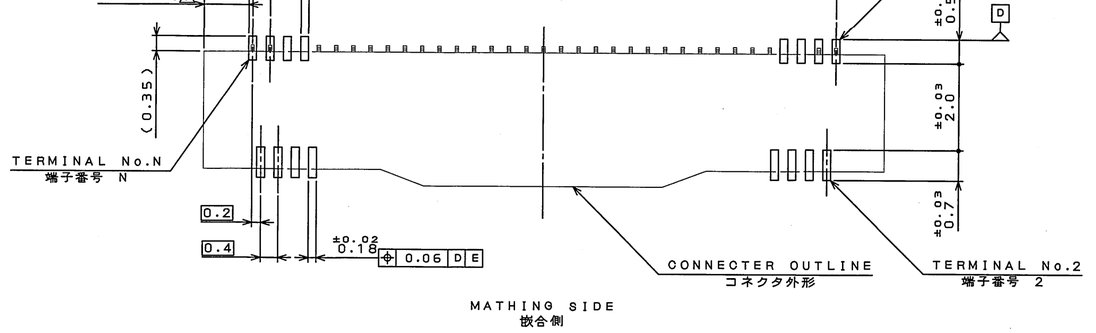
APPLICABLE F.P.C. DIMENSION(REF.)
適合FPC寸法(参考)



DETAIL D
(SCALE 20:1)



SECT. A-A
(SCALE 20:1)



MATHING SIDE
嵌合側

APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

NOTE
1. REFER TO TABLE2 FOR RCOMMENDED FPC COMPOSITION.
2. LOT NUMBER IS MARKED ON THE TOP PORTION OF THE CONNECTOR.
3. A NICKEL BARRIER EXISTS BETWEEN EACH CONTACT POINT AND TAIL.
△4. THE DIMENSIONS OF VACCUMING COVER AREA.
△5. COVERLAY EDGE INCLUDES A PROJECTION OF AN ADHESION LAYER.
△△6. DIMENSION OF TIP IS OPTIONAL WITHIN ABOVE RANGE WITHOUT PATTERN PEELING.

注記
1.推奨FPC構成はTABLE2参照のこと.
2.ロット番号がコネクタ上面に表記される.
3.各コンタクト接点とSMT部の間にはニッケルバリア有り.
△4.吸着エリアを示す.
△5.カバーレイ端面は接着層のはみ出しを含む.
△△6.先端部寸法は上記寸法範囲内で任意とし、パターン剥れ無き事.

TABLE 2. RCOMMENDED FPC COMPOSITION

COMPOSITION 層名		RECOMMENDED 推奨
GOLD PLATING 金めっき	ELECTROLYSIS PLATING 電解めっき	0.1μm MIN
COPPER 銅箔	ROLLED MATERIAL 圧延銅	NOMINAL 18μm MAX
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	— △
BASE FILM ベースフィルム	POLYIMIDE ポリイミド	25μm
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	30μm MAX
REINFORCE PLATE 補強板	POLYIMIDE ポリイミド	—

△TABLE 1.DIMENSIONS

PRODUCT NO.	A	B	C	D
△ FF0825SA1	7.05	4.80	4.80	6.48
△ FF0829SA1	7.85	5.60	5.60	7.28
FF0841SA1	10.25	8.00	8.00	9.68
△ FF0851SA1	12.25	10.00	10.00	11.68
FF0871SA1	16.25	14.00	14.00	15.68
FF0881SA1	18.25	16.00	16.00	17.68

NO.	DESCRIPTION 名称	QTY. 個数	MATERIAL 材料	FINISH 仕上	REMARKS 備考
4	ACTUATOR アクチュエータ	1	HEAT RESISTING PLASTICS 耐熱プラスチック		COLOR:BLACK/色相:黒色 UL94V-0 △△
3	BASE INSULATOR ベースインシュレータ	1	HEAT RESISTING PLASTICS 耐熱プラスチック		COLOR:BEIGE/色相:肌色 UL94V-0 △△
2	CONTACT 2 コンタクト2	(N-1)/2	COPPER ALLOY 銅合金	PARIAL GOLD(0.1μm MIN)OVER NICKEL ニッケル上部分Au 0.1μm以上	
1	CONTACT 1 コンタクト1	(N+1)/2	COPPER ALLOY 銅合金	PARIAL GOLD(0.1μm MIN)OVER NICKEL ニッケル上部分Au 0.1μm以上	

仕様書(SPECIFICATION): △JAOS-10532-* △JAHL-10532
第1版(ORIGINAL DATE): 16.Jul.2008
尺度(SCALE): 10:1
シリーズ(SERIES): FF08
一般公差(GENERAL TOLERANCE)
寸法(DIMENSION): . ±0.8; .× ±0.4; .×× ±0.1; .×××±
角度(ANGLES): X° ±; X°X'±
製図 DR.:
担当 CHK.: K.ASHIBU
査閲 APPD.: K.INOUE
承認 APPD.: Y.MIZUSAWA
名称(TITLE): FF08**SA1 (**:PIN COUNT)
質量(MASS):
日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
図面番号(DRAWING NO.): SJ108178
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SIZE A2

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